

SL110-MS-Q1

List

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings and Electrical characteristics	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6
High reliability test capabilities.....	7

SL110-MS-Q1

1.0A Low VF Surface Mount Schottky Barrier Rectifiers 100V

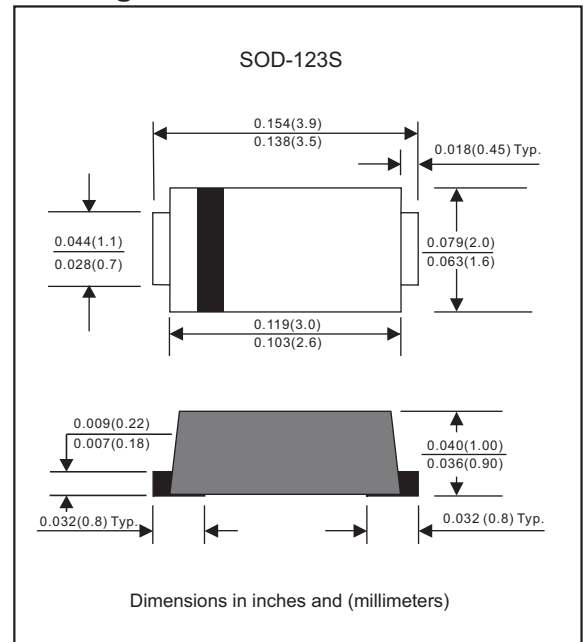
Features

- Very low profile typical height of 0.95mm
- Tiny plastic SMD package
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates halogen free parts, ex. SL110-MS-Q1-H

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123S/MINI SMA
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.0155 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	SL110-MS-Q1	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	100	Volts
Maximum RMS voltage	V_{RMS}	70	Volts
Maximum continuous reverse voltage	V_R	100	Volts
Maximum average forward rectified current	I_o	1.0	Amps
Non-repetitive peak forward surge current 8.3ms single half sine-wave (JEDEC Method)	I_{FSM}	50	Amps
Operating junction temperature range	T_J	-55 to +175	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175	$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	SL110-MS-Q1	UNITS
Maximum instantaneous forward voltage at $I_F=1.0\text{A}$	V_F	0.75	Volts
Maximum reverse leakage current $T_J=25^{\circ}\text{C}$ at rated V_R $T_J=125^{\circ}\text{C}$	I_R	0.05 10	mA mA

Thermal characteristics

PARAMETER	SYMBOLS	SL110-MS-Q1	UNITS
Typical thermal resistance junction to ambient (Note 1)	$R_{\theta JA}$	78	$^{\circ}\text{C/W}$
Typical thermal resistance junction to case (Note 1)	$R_{\theta JC}$	38	$^{\circ}\text{C/W}$

Note 1: Mounted on FR-4 PCB Copper, minimum recommended pad layout.

Rating and characteristic curves (SL110-MS-Q1)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

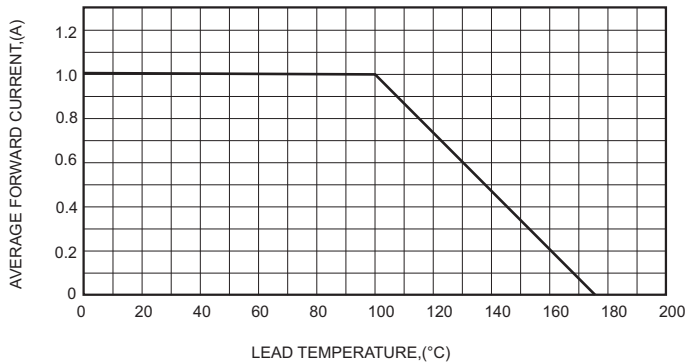


FIG.2-TYPICAL FORWARD CHARACTERISTICS

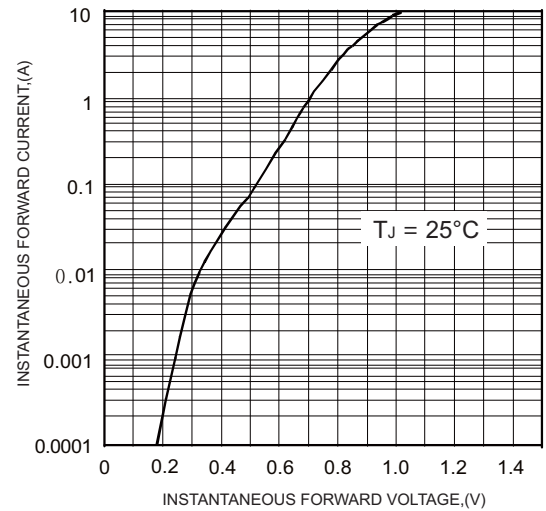


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

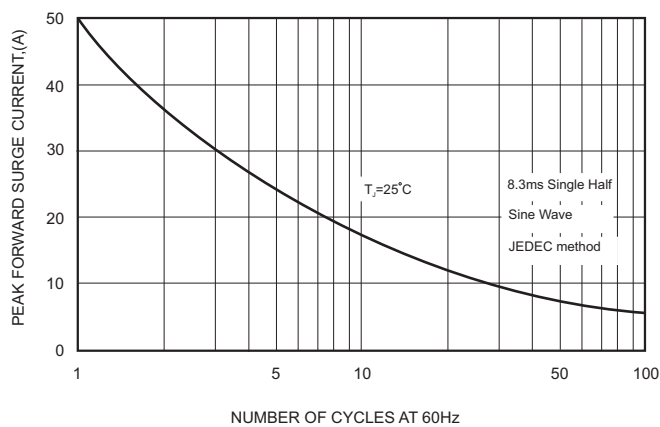


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

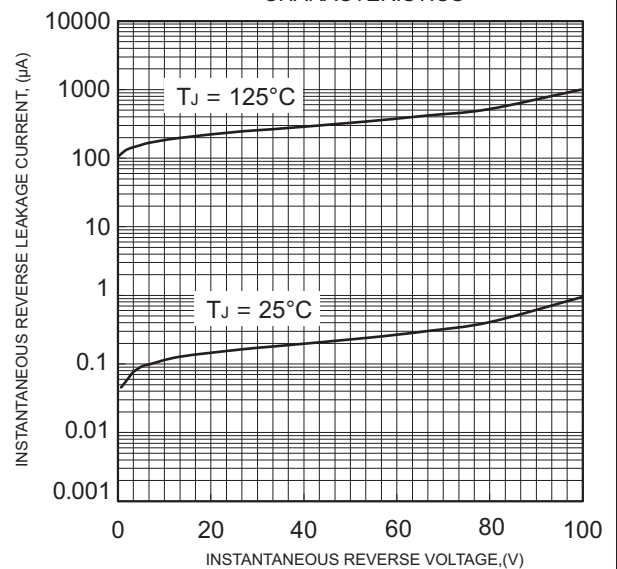
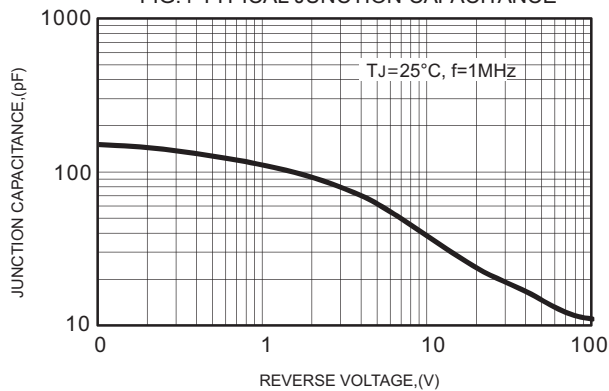


FIG.4-TYPICAL JUNCTION CAPACITANCE



SL110-MS-Q1

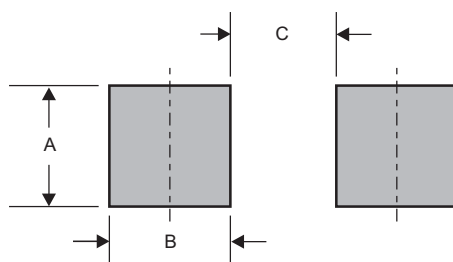
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SL110-MS-Q1	L10

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123S	0.044 (1.10)	0.040 (1.00)	0.079 (2.00)

SL110-MS-Q1

Packing information



unit:mm

Item	Symbol	Tolerance	SOD-123S
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.85
Carrier depth	C	0.1	1.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

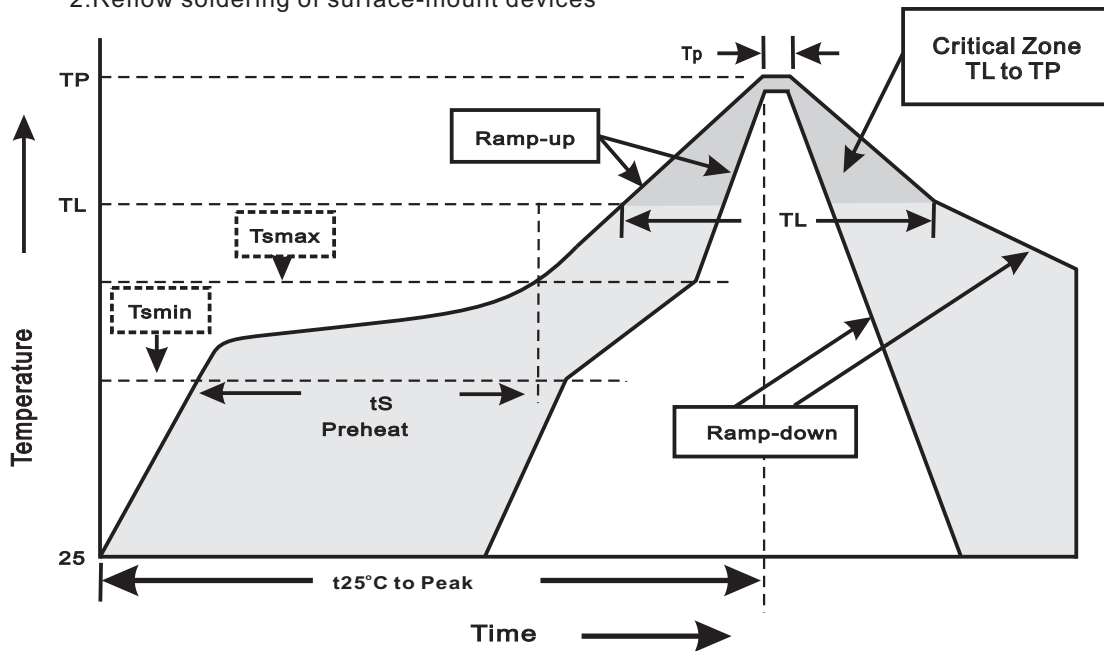
SL110-MS-Q1

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123S	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	9.5

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

SL110-MS-Q1

High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C, Rated Current (Io=Iomax.) Test Duration:1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	VR=VR*100% (TJ=TJmax.) Test Duration:1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=Storage temperature range device specified maximum temperature) Test Duration:1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min) Test Cycles:1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration:96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C, On/Io=Iomax. 2min, Off/2min, Test Cycles:15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245°C±5 for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85%Relative humidity Test Duration:1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260°C±5 for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration:1000hrs	JESD22-A101